Notice for TAIYO YUDEN Products

[For High Quality and/or Reliability Equipment (Automotive Electronic Equipment / Industrial Equipment)]

Please read this notice before using the TAIYO YUDEN products.

!\ REMINDERS

Product information in this catalog is as of October 2018. All of the contents specified herein are subject to change without notice due to technical improvements, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

- Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available.
- Please conduct validation and verification of our products in actual condition of mounting and operating environment before using our products.
- The products listed in this catalog are intended for use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment), medical equipment classified as Class I or II by IMDRF, industrial equipment, and automotive interior applications, etc. Please be sure to contact TAIYO YUDEN for further information before using the products for any equipment which may directly cause loss of human life or bodily injury (e.g., transportation equipment including, without limitation, automotive powertrain control system, train control system, and ship control system, traffic signal equipment, medical equipment classified as Class III by IMDRF).

Please do not incorporate our products into any equipment requiring high levels of safety and/or reliability (e.g., aerospace equipment, aviation equipment*, medical equipment classified as Class IV by IMDRF, nuclear control equipment, undersea equipment, military equipment).

*Note: There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.

When our products are used even for high safety and/or reliability-required devices or circuits of general electronic equipment, it is strongly recommended to perform a thorough safety evaluation prior to use of our products and to install a protection circuit as necessary.

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

- Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.
- Please note that the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a fault or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement.
- The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.
- Caution for Export
 Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

Automotive Application Guide

We classify automotive electronic equipment into the following four application categories and set usable application categories for each of our products. When using our products for automotive electronic equipment, please be sure to check such application categories and use our products accordingly. Should you have any questions on this matter, please contact us.

Category	Automotive Electronic Equipment (Typical Example)
	Engine ECU (Electronically Controlled Fuel Injector)
	Cruise Control Unit
	• 4WS (4 Wheel Steering)
POWERTRAIN	Automatic Transmission
	Power Steering
	HEV/PHV/EV Core Control (Battery, Inverter, DC-DC)
	Automotive Locator (Car location information providing device), etc.
	ABS (Anti-Lock Brake System)
SAFETY	• ESC (Electronic Stability Control)
SALLII	• Airbag
	ADAS (Equipment that directly controls running, turning and stopping), etc.
	• Wiper
	Automatic Door
	• Power Window
	Keyless Entry System
BODY & CHASSIS	• Electric Door Mirror
	• Interior Lighting
	• LED Headlight
	• TPMS (Tire Pressure Monitoring System)
	Anti-Theft Device (Immobilizer), etc.
	Car Infotainment System
INFOTAINMENT	• ITS/Telematics System
	• Instrument Cluster
	• ADAS (Sensor, Equipment that is not interlocked with safety equipment or powertrain), etc.

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MULTILAYER CERAMIC CAPACITORS





■PART NUMBER

J	М	K	3	1	6	Δ	В	J	1	0	6	М	L	Н	Т	Δ
1	2	3		4		5	(3		7		8	9	10	11)	12

△=Blank space

(1)Rate	d voltage

Code	Rated voltage[VDC]
Α	4
J	6.3
L	10
Е	16
Т	25
G	35
U	50
Н	100
Q	250
S	630

3End termination

Code	End termination					
K	Plated					
J	Soft Termination					
S	Cu Internal Electrodes (For High Frequency)					
F High Reliability Application						

	Z/Series name	
	Code	Series name
Ī	М	Multilayer ceramic capacitor
	V	Multilayer ceramic capacitor for high frequency
	W	LW reverse type multilayer capacitor

(4) Dimension (1 x W)

1	4 Dimension (L X	(W)	
	Туре	Dimensions (L×W)[mm]	EIA (inch)
	063	0.6 × 0.3	0201
	105	1.0 × 0.5	0402
		0.52 × 1.0 ※	0204
	107	1.6 × 0.8	0603
		0.8 × 1.6 ※	0306
	010	2.0 × 1.25	0805
	212	1.25 × 2.0 💥	0508
	316	3.2 × 1.6	1206
	325	3.2 × 2.5	1210
	432	4.5 × 3.2	1812

Note: ※LW reverse type(□WK) only

5Dimension tolerance

Code	Туре	L[mm]	W[mm]	T[mm]
Δ	ALL	Standard	Standard	Standard
	063	0.6±0.05	0.3±0.05	0.3±0.05
	105	1.0±0.10	0.5±0.10	0.5±0.10
	107	1.6+0.15/-0.05	0.8+0.15/-0.05	0.8+0.15/-0.05
Α	212	2.0+0.15/-0.05	1.25+0.15/-0.05	0.85±0.10
	212	2.0+0.19/ -0.05	1.25 + 0.15/ - 0.05	1.25+0.15/-0.05
	316	3.2±0.20	1.6±0.20	1.6±0.20
	325	3.2±0.30	2.5±0.30	2.5±0.30
	105	1.0+0.15/-0.05	0.5+0.15/-0.05	0.5+0.15/-0.05
	107	1.6+0.20/-0	0.8+0.20/-0	0.8+0.20/-0
В	212	2.0+0.20/-0	1.25+0.20/-0	0.85±0.10
	212	2.0+0.20/ -0	1.25 + 0.20/ - 0	1.25+0.20/-0
	316	3.2±0.30	1.6±0.30	1.6±0.30
	105	1.0+0.20/-0	0.5+0.20/-0	0.5+0.20/-0
С	107	1.6+0.25/-0	0.8+0.25/-0	0.8+0.25/-0
	212	2.0+0.25/-0	1.25+0.25/-0	1.25+0.25/-0
	212	2.0±0.15	1.25±0.15	0.85±0.15
K	316	3.2±0.20	1.6±0.20	1.15±0.20
r.	310	3.2 ± 0.20	1.0 ± 0.20	1.6±0.20
	325	3.2±0.50	2.5±0.30	2.5±0.30

Note: cf. STANDARD EXTERNAL DIMENSIONS

Δ= Blank space

6Temperature characteristics code

■High dielectric type

Code	Applicable				Applicable standard		Temperature range[°C]	Ref. Temp.[°C]	Capacitance change	Capacitance tolerance	Tolerance code
				0.5	1.450/	±10%	K				
BJ	EIA	X5R	−55 ~ + 85	25	±15%	±20%	М				
C6	EIA	X6S	-55 ~ +105	25	±22%	±10%	K				
	LIA	703	33.4 103	23	± 22 70	±20%	М				
В7	EIA	X7R	-55~+125 25 ±15%	±10%	K						
	LIA	X/IX	33.4 1 123	23	±1370	±20%	М				
C7	EIA	X7S	-55 ~ +125	25	±22%	±10%	K				
	LIA	7/3	33.4 1 123	23	1 22 %	±20%	М				
D7 E	EIA	EIA V7T	EIA X7T —5	-55 ~ +125	25	+22%/-33%	±10%	K			
	ĭ	A/1	35.4 1 123	25	1 22 70/ 33 70	±20%	М				

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■Temperature compensating type

Code		cable dard	Temperature range [°C]	Ref. Temp.[°C]	Capacitance change	Capacitance tolerance	Tolerance code
						±0.1pF	В
	JIS	CG		20		±0.25pF	С
CG			-55 ~ +125		0±30ppm/°C	±0.5pF	D
CG			-55~+125			±1pF	F
	EIA	C0G		25		±2%	G
						±5%	J

7Nominal capacitance

Code (example)	Nominal capacitance
0R5	0.5pF
010	1pF
100	10pF
101	100pF
102	1,000pF
103	0.01 <i>μ</i> F
104	0.1 μ F
105	1.0 <i>μ</i> F
106	10 μ F
107	100 μ F

Note: R=Decimal point

8 Capacitance tolerance

Code	Capacitance tolerance
Α	±0.05pF
В	±0.1pF
С	±0.25pF
D	±0.5pF
G	±2%
J	±5%
K	±10%
М	±20%

Thickness

Code	Thickness[mm]
Р	0.3
Т	0.3
V	0.5
С	0.7(107type or more)
Α	0.8
D	0.85(212type or more)
F	1.15
G	1.25
L	1.6
N	1.9
M	2.5

®Special code

Code	Special code
Н	MLCC for Industrial and Automotive

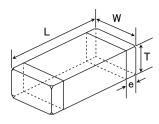
11)Packaging

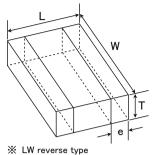
O:	
Code	Packaging
F	ϕ 178mm Taping (2mm pitch)
R	ϕ 178mm Embossed Taping (4mm pitch)
Т	φ 178mm Taping (4mm pitch)
P	ϕ 178mm Taping (4mm pitch, 1000 pcs/reel)
•	325 type (Thickness code M)

12Internal code

Garresinar seas	
Code	Internal code
Δ	Standard

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		Dime	nsion [mm] (inch)			
Type(EIA)	L	W	T	*1	е	
□MK063(0201)	0.6±0.03 (0.024±0.001)	0.3±0.03 (0.012±0.001)	0.3±0.03 (0.012±0.001)	Т	0.15±0.05 (0.006±0.002)	
□MK105(0402) □MF105(0402)	1.0±0.05 (0.039±0.002)	0.5±0.05 (0.020±0.002)	0.5±0.05 (0.020±0.002)	٧	0.25±0.10 (0.010±0.004)	
□WK105(0204)※	0.52±0.05 (0.020±0.002)	1.0±0.05 (0.039±0.002)	0.3±0.05 (0.012±0.002)	Р	0.18±0.08 (0.007±0.003)	
□MK107(0603) □MF107(0603)	1.6±0.10 (0.063±0.004)	0.8±0.10 (0.031±0.004)	0.8±0.10 (0.031±0.004)	Α	0.35±0.25 (0.014±0.010)	
□MJ107(0603)	1.6±0.10 (0.063±0.004)	0.8±0.10 (0.031±0.004)	0.8±0.10 (0.031±0.004)	Α	0.35+0.3/-0.25 (0.014+0.012/-0.010)	
□VS107(0603)	1.6±0.10 (0.063±0.004)	0.8±0.10 (0.031±0.004)	0.7±0.10 (0.028±0.004)	С	0.35±0.25 (0.014±0.010)	
□WK107(0306)※	0.8±0.10 (0.031±0.004)	1.6±0.10 (0.063±0.004)	0.5±0.05 (0.020±0.002)	٧	0.25±0.15 (0.010±0.006)	
□MK212(0805)	2.0±0.10	1.25±0.10	0.85±0.10 (0.033±0.004)	D	0.5±0.25	
□MF212(0805)	(0.079±0.004)	(0.049±0.004)	1.25±0.10 (0.049±0.004)	G	(0.020±0.010)	
	2.0±0.10	1.25±0.10	0.85±0.10 (0.033±0.004)	D	0.5+0.35/-0.25	
□MJ212(0805)	(0.079 ± 0.004)	(0.049±0.004)	1.25±0.10 (0.049±0.004)	G	(0.020+0.014/-0.010)	
□VS212(0805)	2.0±0.10 (0.079±0.004)	1.25±0.10 (0.049±0.004)	0.85±0.10 (0.033±0.004)	D	0.5±0.25 (0.020±0.010)	
□WK212(0508)※	1.25±0.15 (0.049±0.006)	2.0±0.15 (0.079±0.006)	0.85±0.10 (0.033±0.004)	D	0.3±0.2 (0.012±0.008)	
□MK316(1206)	3.2±0.15	1.6±0.15	1.15±0.10 (0.045±0.004)	F	0.5+0.35/-0.25	
□MF316(1206)	(0.126 ± 0.006)	(0.063±0.006)	1.6±0.20 (0.063±0.008)	L	(0.020+0.014/-0.010)	
□MJ316(1206)	3.2±0.15	1.6±0.15	1.15±0.10 (0.045±0.004)	F	0.6+0.4/-0.3	
ШМЈ316(1206)	(0.126±0.006)	(0.063±0.006)	1.6±0.20 (0.063±0.008)	L	(0.024+0.016/-0.012)	
			1.15±0.10 (0.045±0.004)	F		
□MK325(1210) □MF325(1210)	3.2±0.30 (0.126±0.012)	2.5±0.20 (0.098±0.008)	1.9±0.20 (0.075±0.008)	N	0.6±0.3 (0.024±0.012)	
			2.5±0.20 (0.098±0.008)	М		
ПМ 1225 (1210)	3.2±0.30	2.5±0.20	1.9±0.20 (0.075±0.008)	N	0.6+0.4/-0.3	
□MJ325(1210)	(0.126±0.012)	(0.098±0.008)	2.5±0.20 (0.098±0.008)	М	(0.024 + 0.016 / -0.012)	
□MK432(1812)	4.5±0.40	3.2±0.30	2.5±0.20	М	0.9±0.6	

 (0.098 ± 0.008)

 (0.035 ± 0.024)

(0.177±0.016) (0.126 ± 0.012) Note : X. LW reverse type, *1.Thickness code

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STANDARD QUANTITY

Time	EIA (inch)	Dime	nsion	Standard qu	uantity[pcs]	
Type	EIA (Inch)	[mm]	Code	Paper tape	Embossed tape	
063	0201	0.3	Т	15000	_	
105	0402	0.5	٧	10000		
105	0204 ※	0.30	Р	С	_	
		0.7	С	4000	_	
		0.8	Α	4000	_	
	0603	0.0	Α	3000		
107	0003	0.8	A	(Soft Termination)	_	
		0.8 A	٨	_	3000	
		0.8 A		_	(Soft Termination)	
	0306 ※	0.50	٧	_	4000	
		0.85	D	4000	_	
	0805	1.25	G	_	3000	
212	0803	1.25	G		2000	
		1.20	G	_	(Soft Termination)	
	0508 ※	0.85	D	4000	_	
316	1006	1.15	F	_	3000	
310	1206	1.6	L	_	2000	
		1.15	F		2000	
325	1210	1.9 N		_	2000	
		2.5	М	_	500(T), 1000(P)	
432	1812	2.5	М	_	500	

Note : ※.LW Reverse type(□WK)

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Soft Termination Multilayer Ceramic Capacitors

●107TYPE (Dimension:1.6 × 0.8mm JIS:1608 EIA:0603)

[Temperature Characteristic B7 : $X7R(-55 \sim +125^{\circ}C)$] 0.8mm thickness(A)

Dest south of	D	Rated voltage	Tempe	erature	Capacitance	Capacitance	tan δ	HTLT	*3 5 3	Note
Part number 1	Part number 2	[V]	charact	eristics	[F]	tolerance [%]	[%]	Rated voltage x %	Thickness*3 [mm]	Note
TMJ107BB7473[]AHT				X7R	0.047 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
TMJ107BB7104∏AHT				X7R	0.1 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
TMJ107BB7224 AHT		25		X7R	0.22 μ	±10, ±20	10	150	0.8+0.20/-0	*1, *2
TMJ107BB7474 AHT				X7R	0.47 μ	±10, ±20	10	150	0.8+0.20/-0	*1, *2
TMJ107CB7105∏AHR				X7R	1 μ	±10, ±20	10	150	0.8+0.25/-0	*1, *2
GMJ107BB7473□AHT				X7R	0.047 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
GMJ107BB7104□AHT				X7R	0.1 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
GMJ107BB7224□AHT		35		X7R	0.22 μ	±10, ±20	10	150	0.8+0.20/-0	*1, *2
GMJ107BB7474□AHT				X7R	0.47 μ	±10, ±20	10	150	0.8+0.20/-0	*1, *2
GMJ107CB7105∏AHR				X7R	1 μ	±10, ±20	10	150	0.8+0.25/-0	*1, *2
UMJ107AB7102□AHT				X7R	1000 p	±10, ±20	3.5	200	0.8+0.15/-0.05	*1, *2
UMJ107AB7222∏AHT				X7R	2200 p	±10, ±20	3.5	200	0.8+0.15/-0.05	*1, *2
UMJ107BB7472∏AHT				X7R	4700 p	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
UMJ107BB7103[AHT		50		X7R	0.01 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
UMJ107BB7223[]AHT				X7R	0.022 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
UMJ107BB7473[]AHT				X7R	0.047 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
UMJ107BB7104[]AHT				X7R	0.1 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
HMJ107AB7102∏AHT				X7R	1000 p	±10, ±20	3.5	200	0.8+0.15/-0.05	*1, *2
HMJ107AB7222∏AHT				X7R	2200 p	±10, ±20	3.5	200	0.8+0.15/-0.05	*1, *2
HMJ107BB7472[]AHT				X7R	4700 p	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
HMJ107BB7103[]AHT		100		X7R	0.01 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
HMJ107BB7223[]AHT				X7R	0.022 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
HMJ107BB7473∏AHT		1		X7R	0.047 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2
HMJ107BB7104[]AHT				X7R	0.1 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1, *2

212TYPE (Dimension:2.0 × 1.25mm JIS:2012 EIA:0805)

 $\begin{tabular}{l} \textbf{[} Temperature Characteristic B7: X7R(-55~+125^{\circ}C), C7: X7S(-55~+125^{\circ}C)] & 0.85mm thickness(D), 1.25mm thickness(G) \\ \end{tabular}$

Part number 1	Part number 2	Rated voltage			Capacitance	Capacitance	tan δ	HTLT	Thickness*3 [mm]	Note
Part number 1	Part number 2	[V]	charact	eristics	[F]	tolerance [%]	[%]	Rated voltage x %	Thickness [mm]	Note
JMJ212CB7106 GHT		6.3		X7R	10 μ	±10, ±20	10	150	1.25+0.25/-0	*1, *2
EMJ212CB7225∏GHT		16		X7R	2.2 μ	±10, ±20	10	150	1.25+0.25/-0	*1, *2
EMJ212CB7475 GHT		10		X7R	4.7 μ	±10, ±20	10	150	1.25+0.25/-0	*1, *2
TMJ212CB7225 GHT		25		X7R	2.2 μ	±10, ±20	10	150	1.25+0.25/-0	*1, *2
GMJ212CB7105∏GHT		35		X7R	1 μ	±10, ±20	10	150	1.25+0.25/-0	*1, *2
UMJ212BB7103[]GHT				X7R	0.01 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1, *2
UMJ212BB7223[]GHT				X7R	0.022 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1, *2
UMJ212BB7473[]GHT				X7R	0.047 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1, *2
UMJ212BB7104[]GHT		50		X7R	0.1 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1, *2
UMJ212BB7224[]GHT				X7R	0.22 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1, *2
UMJ212CC7474[]GHTE				X7S	0.47 μ	±10, ±20	3.5	150	1.25+0.25/-0	*1, *2
UMJ212CB7105∏GHT				X7R	1 μ	±10, ±20	10	150	1.25+0.25/-0	*1, *2
HMJ212KB7102 DHT				X7R	1000 p	±10, ±20	3.5	200	0.85±0.15	*1, *2
HMJ212KB7222 DHT				X7R	2200 p	±10, ±20	3.5	200	0.85 ± 0.15	*1, *2
HMJ212BB7472∏GHT				X7R	4700 p	±10, ±20	3.5	200	1.25+0.20/-0	*1, *2
HMJ212BB7103∏GHT				X7R	0.01 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1, *2
HMJ212BB7223∏GHT		100		X7R	0.022 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1, *2
HMJ212BB7473∏GHT				X7R	0.047 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1, *2
HMJ212BB7104 GHT				X7R	0.1 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1, *2
HMJ212BB7224 GHT				X7R	0.22 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1, *2
HMJ212CC7474[]GHTE				X7S	0.47 μ	±10, ±20	3.5	150	1.25+0.25/-0	*1, *2
QMJ212KB7102 DHT				X7R	1000 p	±10, ±20	2.5	150	0.85 ± 0.15	*1, *2
QMJ212KB7222 DHT				X7R	2200 p	±10, ±20	2.5	150	0.85±0.15	*1, *2
QMJ212BB7472 GHT		250		X7R	4700 p	±10, ±20	2.5	150	1.25+0.20/-0	*1, *2
QMJ212BB7103 GHT				X7R	0.01 μ	±10, ±20	2.5	150	1.25+0.20/-0	*1, *2
QMJ212BB7223[]GHT				X7R	0.022 μ	±10, ±20	2.5	150	1.25+0.20/-0	*1, *2

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316TYPE (Dimension:3.2 × 1.6mm JIS:3216 EIA:1206)

[Temperature Characteristic B7: X7R(-55~+125°C), C7: X7S(-55~+125°C)] 1.15mm thickness(F), 1.6mm thickness(L)

I Temperature Charac	cteristic b/: A/R(-	-33~ + 123 (5), 67:	X/3(-	35~ + 125 C/]	1.15mm thickne	ess(r), i.	omm thickness (L)	
Part number 1	Part number 2	Rated voltage	Tempe	erature	Capacitance	Capacitance	tan δ	HTLT	Thickness*3 [mm]	Note
Fart number 1	Fart Humber 2	[V]	charac	teristics	[F]	tolerance [%]	[%]	Rated voltage x %	Thickness [mm]	Note
LMJ316BB7226 LHT		10		X7R	22 μ	±10, ±20	10	150	1.6±0.30	*1, *2
EMJ316BB7475[]LHT		16		X7R	4.7 μ	±10, ±20	10	150	1.6±0.30	*1, *2
EMJ316BB7106[]LHT		10		X7R	10 μ	±10, ±20	10	150	1.6±0.30	*1, *2
TMJ316BB7474 LHT				X7R	0.47 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
TMJ316BB7475[LHT		25		X7R	4.7 μ	±10, ±20	10	150	1.6±0.30	*1, *2
TMJ316BB7106[LHT		Ī		X7R	10 μ	±10, ±20	10	150	1.6±0.30	*1, *2
GMJ316BB7474□LHT				X7R	0.47 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
GMJ316AB7225 LHT		35		X7R	2.2 μ	±10, ±20	10	150	1.6±0.20	*1, *2
GMJ316BB7475 LHT		33		X7R	4.7 μ	±10, ±20	10	150	1.6±0.30	*1, *2
GMJ316BB7106□LHT		1		X7R	10 μ	±10, ±20	10	150	1.6±0.30	*1, *2
UMJ316BB7473[]LHT				X7R	0.047 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
UMJ316BB7104[]LHT		Ī		X7R	0.1 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
UMJ316BB7224[]LHT		Ī		X7R	0.22 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
UMJ316BB7474[]LHT		50		X7R	0.47 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
UMJ316BB7105[]LHT				X7R	1 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
UMJ316AB7225[]LHT		1		X7R	2.2 μ	±10, ±20	10	150	1.6±0.20	*1, *2
UMJ316BC7475[LHTE				X7S	4.7 μ	±10, ±20	2.5	150	1.6±0.30	*1, *2
HMJ316 B7102[FHT				X7R	1000 p	±10, ±20	3.5	200	1.15±0.10	*1, *2
HMJ316 B7222[]FHT		1		X7R	2200 p	±10, ±20	3.5	200	1.15±0.10	*1, *2
HMJ316 B7472[FHT		1		X7R	4700 p	±10, ±20	3.5	200	1.15±0.10	*1, *2
HMJ316KB7103[FHT		1		X7R	0.01 μ	±10, ±20	3.5	200	1.15±0.20	*1, *2
HMJ316BB7223[]LHT]		X7R	0.022 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
HMJ316BB7473[LHT		100		X7R	0.047 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
HMJ316BB7104[]LHT		1		X7R	0.1 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
HMJ316BB7224[]LHT		1		X7R	0.22 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
HMJ316BB7474[]LHT		1		X7R	0.47 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
HMJ316BB7105[]LHT		1		X7R	1 μ	±10, ±20	3.5	200	1.6±0.30	*1, *2
HMJ316BC7225□LHTE				X7S	2.2 μ	±10, ±20	3.5	150	1.6±0.30	*1, *2
QMJ316 B7102 FHT		1		X7R	1000 p	±10, ±20	2.5	150	1.15±0.10	*1, *2
QMJ316 B7222 FHT		1		X7R	2200 p	±10, ±20	2.5	150	1.15±0.10	*1, *2
QMJ316 B7472 FHT				X7R	4700 p	±10, ±20	2.5	150	1.15±0.10	*1, *2
QMJ316KB7103[FHT		250		X7R	0.01 μ	±10, ±20	2.5	150	1.15±0.20	*1, *2
QMJ316BB7223 LHT		1		X7R	0.022 μ	±10, ±20	2.5	150	1.6±0.30	*1, *2
QMJ316BB7473[]LHT		1		X7R	0.047 μ	±10, ±20	2.5	150	1.6±0.30	*1, *2
QMJ316BB7104[]LHT				X7R	0.1 μ	±10, ±20	2.5	150	1.6±0.30	*1, *2
SMJ316 B7102[]FHT	•	1		X7R	1000 p	±10, ±20	2.5	120	1.15±0.10	*1, *2
SMJ316 B7222[]FHT	•	1		X7R	2200 p	±10, ±20	2.5	120	1.15±0.10	*1, *2
SMJ316 B7472[FHT		630		X7R	4700 p	±10, ±20	2.5	120	1.15±0.10	*1, *2
SMJ316KB7103[FHT		1		X7R	0.01 μ	±10, ±20	2.5	120	1.15±0.20	*1, *2
SMJ316BB7223[]LHT				X7R	0.022 μ	±10, ±20	2.5	120	1.6±0.30	*1, *2

325TYPE (Dimension:3.2 × 2.5mm JIS:3225 EIA:1210)

[Temperature Characteristic B7 : X7R($-55 \sim +125^{\circ}$ C), C7 : X7S($-55 \sim +125^{\circ}$ C)] 1.9mm thickness(N), 2.5mm thickness(M)

Part number 1	Part number 2	Rated voltage	Tempe	rature	Capacitance	Capacitance	$ an\delta$	HTLT	Thickness*3 [mm]	Note
Part number 1	Part number 2	[V]	charact	eristics	[F]	tolerance [%]	[%]	Rated voltage x %	Thickness [mm]	Note
JMJ325KB7476 MHP		6.3		X7R	47 μ	±10, ±20	10	150	2.5 ± 0.30	*1, *2
EMJ325KB7226 MHP		16		X7R	22 μ	±10, ±20	10	150	2.5 ± 0.30	*1, *2
TMJ325AB7475[]MHP		25		X7R	4.7 μ	±10, ±20	5	150	2.5±0.30	*1, *2
TMJ325KB7106□MHP		25		X7R	10 μ	±10, ±20	10	150	2.5±0.30	*1, *2
GMJ325AB7475 MHP		35		X7R	4.7 μ	±10, ±20	5	150	2.5±0.30	*1, *2
GMJ325KB7106[]MHP		33		X7R	10 μ	±10, ±20	10	150	2.5 ± 0.30	*1, *2
UMJ325AB7225[]MHP				X7R	2.2 μ	±10, ±20	3.5	200	2.5 ± 0.30	*1, *2
UMJ325AB7475[]MHP		50		X7R	4.7 μ	$\pm 10, \pm 20$	5	150	2.5±0.30	*1, *2
UMJ325KB7106 MHP				X7R	10 μ	$\pm 10, \pm 20$	10	150	2.5 ± 0.30	*1, *2
HMJ325 B7223[NHT		1		X7R	0.022 μ	$\pm 10, \pm 20$	3.5	200	1.9±0.20	*1, *2
HMJ325 B7473[NHT		1		X7R	0.047 μ	$\pm 10, \pm 20$	3.5	200	1.9±0.20	*1, *2
HMJ325 B7104[NHT		1		X7R	0.1 μ	$\pm 10, \pm 20$	3.5	200	1.9±0.20	*1, *2
HMJ325 B7224[NHT		100		X7R	0.22 μ	$\pm 10, \pm 20$	3.5	200	1.9±0.20	*1, *2
HMJ325 B7474[NHT		100		X7R	0.47 μ	±10, ±20	3.5	200	1.9±0.20	*1, *2
HMJ325 B7105[NHT				X7R	1 μ	±10, ±20	3.5	200	1.9±0.20	*1, *2
HMJ325AB7225[MHP				X7R	2.2 μ	±10, ±20	3.5	200	2.5±0.30	*1, *2
HMJ325KC7475[]MHPE				X7S	4.7 μ	±10, ±20	3.5	150	2.5±0.30	*1, *2
QMJ325 B7223[NHT				X7R	0.022 μ	±10, ±20	2.5	150	1.9±0.20	*1, *2
QMJ325 B7473[NHT		250		X7R	0.047 μ	±10, ±20	2.5	150	1.9±0.20	*1, *2
QMJ325 B7104[NHT		230		X7R	0.1 μ	±10, ±20	2.5	150	1.9±0.20	*1, *2
QMJ325 B7224[NHT				X7R	0.22 μ	±10, ±20	2.5	150	1.9±0.20	*1, *2
SMJ325 B7223[NHT		630		X7R	0.022 μ	±10, ±20	2.5	120	1.9±0.20	*1, *2
SMJ325 B7473[]NHT		000		X7R	0.047 μ	±10, ±20	2.5	120	1.9±0.20	*1, *2

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Multilayer Ceramic Capacitors

■PACKAGING

1 Minimum Quantity

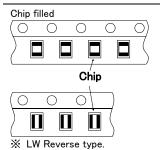
Taped package	TILL		0, 1, 1	en F 3
Type(EIA)	Thick mm	code	Paper tape	uantity [pcs] Embossed tape
□MK021(008004)	0.125	K	- парет саре	50000
□VS021(008004)	0.123	IX		30000
☐MK042(01005)	0.2	C, D	_	40000
□VS042(01005)	0.2	С	_	40000
☐MK063(0201)	0.3	P,T	15000	_
□WK105(0204) ※	0.3	Р	10000	_
	0.13	Н	_	20000
DM(105(0400)	0.18	E	_	15000
☐MK105(0402) ☐MF105(0402)	0.2	С	20000	_
MF 105(0402)	0.3	Р	15000	_
	0.5	V	10000	_
□VK105(0402)	0.5	W	10000	_
□MK107(0603)	0.45	K	4000	_
□WK107(0306) ※	0.5	V	_	4000
□MF107(0603)	0.8	Α	4000	_
□VS107(0603)	0.7	С	4000	_
□MJ107(0603)	0.8	Α	3000	3000
□MK212(0805)	0.45	K	4000	
□WK212(0508) ※	0.85	D	4000	_
□MF212(0805)	1.25	G	_	3000
□VS212(0805)	0.85	D	4000	_
	0.85	D	4000	_
□MJ212(0805)	1.25	G	_	2000
	0.85	D	4000	_
□MK316(1206)	1.15	F	_	3000
□MF316(1206)	1.6	L	_	2000
	1.15	F	_	3000
□MJ316(1206)	1.6	L	_	2000
	0.85	D		
	1.15	F	1	
☐MK325(1210)	1.9	N	1 -	2000
□MF325(1210)	2.0max.	Y	1	
	2.5	M	_	1000
[] 1 1005(1015)	1.9	N	_	2000
□MJ325(1210)	2.5	М	_	500(T), 1000(P)
□MK432(1812)	2.5	М	_	500

Note:

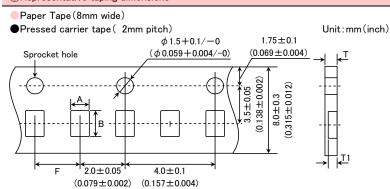
K LW Reverse type.

**No bottom tape for pressed carrier tape Card board carrier tape Top tape Base tape Sprocket hole Chip cavity Base tape Chip cavity

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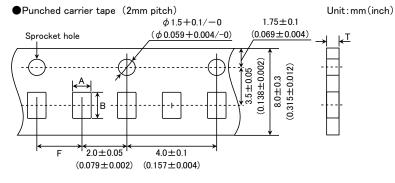
3 Representative taping dimensions



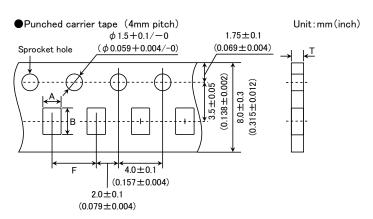
Type(EIA)	Chip	Cavity	Insertion Pitch	Tape Thickness		
Type(EIA)	Α	В	F	Т	T1	
□MK063(0201)	0.37	0.67		0.45max.	0.42max.	
□WK105(0204) ※			2.0±0.05	0.45max.	0.42max.	
□MK105(0402) (*1 C)	0.65	1.15	1.15	2.0 ± 0.00	0.4max.	0.3max.
□MK105(0402) (*1 P)				0.45max.	0.42max.	

Note *1 Thickness, C:0.2mm ,P:0.3mm. * LW Reverse type.

Unit:mm



Type(EIA)	Chip	Cavity	Insertion Pitch	Tape Thickness
Type(EIA)	Α	В	F	Т
☐MK105 (0402)				
☐MF105 (0402)	0.65	1.15	2.0 ± 0.05	0.8max.
□VK105 (0402)				
	•			Unit:mm

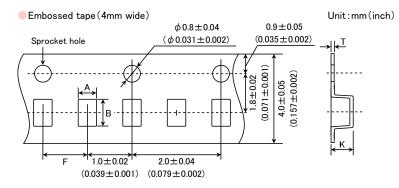


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Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness
Type(EIA)	Α	В	F	Т
☐MK107(0603)				
□WK107(0306) ※	1.0	1.8		1.1max.
☐MF107(0603)			40+01	
☐MK212(0805)	1.65	0.4	4.0±0.1	
□WK212(0508) ※	1.65	2.4		1.1max.
☐MK316(1206)	2.0	3.6		

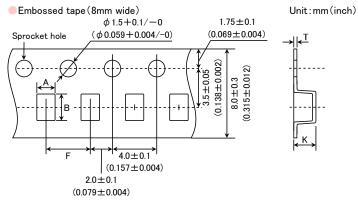
Note: Taping size might be different depending on the size of the product. X LW Reverse type.

Unit:mm



Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness		
Type(EIA)	Α	В	F	K	Т	
☐MK021(008004)	0.135	0.27				
□VS021(008004)	0.135	0.27	101000	0.5	0.25max.	
☐MK042(01005)	0.23	0.40	1.0±0.02	0.5max.		
□VS042(01005)	0.23	0.43				

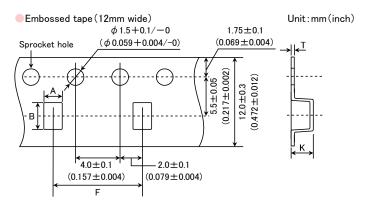
Unit:mm



Type(EIA)	Chip (Chip Cavity		Tape Thickness	
Type(EIA)	Α	В	F	K	Т
☐MK105(0402)	0.6	1.1	2.0±0.1	0.6max	0.2±0.1
□WK107(0306) ※	1.0	1.8		1.3max.	0.25±0.1
☐MK212(0805) ☐MF212(0805)	1.65	2.4			
☐MK316(1206) ☐MF316(1206)	2.0	3.6	4.0±0.1	3.4max.	0.6max.
☐MK325(1210) ☐MF325(1210)	2.8	3.6]		

Note: ※ LW Reverse type. Unit:mm

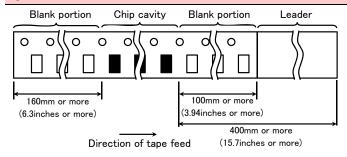
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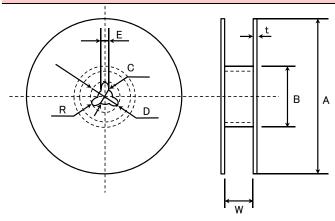
Type(EIA)	Chip Cavity		Insertion Pitch	Tape Th	nickness
Type(EIA)	Α	В	F	K T	
☐MK325(1210)	3.1	4.0	8.0±0.1	4.0max.	0.6max.
☐MK432(1812)	3.7	4.9	8.0±0.1	4.0max.	0.6max.

Unit:mm

4 Trailer and Leader



⑤Reel size



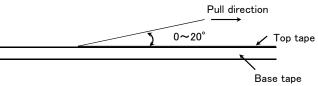
Α	В	С	D	Е	R
ϕ 178 ± 2.0	<i>ф</i> 50min.	ϕ 13.0 \pm 0.2	ϕ 21.0 ± 0.8	2.0±0.5	1.0

	T	W
4mm wide tape	1.5max.	5±1.0
8mm wide tape	2.5max.	10±1.5
12mm wide tape	2.5max.	14±1.5

Unit:mm

®Top Tape Strength

The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.



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Multilayer Ceramic Capacitors

■RELIABILITY DATA

	mperature Range	Standard					
	Temperature Compensating(Class1)		−55 to +	-125°C			
	Compensating (Class I)	High Frequency Type					
				Specification	Temperature Range)	
			BJ	В	−25 to +85°C		
pecified	ecified			X5R	-55 to +85°C		
/alue			B7	X7R	−55 to +125°C		
	High Permittivity (Class2)		C6	X6S	−55 to +105°C		
			C7	X7S	-55 to +125℃		
			D7	X7T	-55 to +125°C		
			LD(※)	X5R	−55 to +85°C		
			Note: 🔆	LD Low distortion hi	gh value multilayer ceran	nic capacito	
Storage Cor	nditions						
	T	Standard					
	Compensating(Class1)	Comporator (OL 1)		-125°C			
	Compensating (Class I)	High Frequency Type					
				Specification	Temperature Range	÷	
			BJ	В	−25 to +85°C		
pecified		В	X5R	−55 to +85°C			
alue			B7	X7R	−55 to +125°C		
	High Permittivity (Class2))	C6	X6S	-55 to +105°C		
			C7	X7S	−55 to +125°C		
			D7	X7T	−55 to +125°C		
			LD(※)	X5R	−55 to +85°C		
			Note: 🔆	LD Low distortion hi	gh value multilayer ceran	nic capacit	
			•				
Rated Voltag	Υ <u>Α</u>						
Mateu Volta		0	50) (D.O. 05				
Specified	Temperature	Standard	50VDC, 25VDC				
/alue	Compensating(Class1)	High Frequency Type	50VDC, 25VDC				
2.00	High Permittivity (Class2)		50VDC, 35	50VDC, 35VDC, 25VDC, 16VDC, 10VDC, 6.3VDC, 4VDC, 2.5VDC			
Withstanding	y Voltage (Between terminal	2)					
. withstanding	voltage (between terminal						
D	Temperature	Standard					
Specified	Compensating(Class1) High Frequency Type		No breakdo	own or damage			
'alue	High Permittivity (Class2)						
	, ,		ass 1		ass 2		
est	Applied voltage				ass 2 oltage × 2.5		
ฮรเ	Applied voltage Rated				ortage ^ Z.0		
	Duration	Duration		1 to 5 sec.			
lethods and emarks	Duration Charge/discharge currer			50mA max.			

Standard Temperature 10000 $M\,\Omega$ min. ${\sf Compensating}({\sf Class1})$ High Frequency Type Specified Value C \leq 0.047 μ F : 10000 M Ω min. High Permittivity (Class2) Note 1 C>0.047 μ F : 500M Ω • μ F : Rated voltage Test Applied voltage Methods and Duration : 60±5 sec. Remarks Charge/discharge current : 50mA max.

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6. Capacitance	(Tolerance)						
Temperature	Standard	C □ U □ SL	0.2pF≦C≦5pF 0.2pF≦C≦10pF C>10pF	: ±0.25pF : ±0.5pF : ±5% or ±10%			
Specified Value		High Frequency Type	СН	0.3pF≦C≦2pF C>2pF	: ±0.1pF : ±5%		
	High Permittivity (Class2)		BJ, B7, C6, C7, D7, LD($\%$): $\pm 10\%$ or $\pm 20\%$ Note: $\%$ LD Low distortion high value multilayer ceramic capacitor				
			Class 1		Cla	ass 2	
.		Standard	t	High Frequency Type	C≦10 µF	C>10 µF	
Test Methods and	Preconditioning		Noi	ne	Thermal treatment (a	t 150°C for 1hr) Note 2	
Remarks	Measuring frequency		1MHz±10%		1kHz±10%	120±10Hz	
Remarks	Measuring voltage Note		0.5 to 5	5Vrms	1±0.2Vrms	0.5±0.1rms	
	Bias application				one		

Temperature Specified	•	Standard		C < 30pF : Q ≥ 400 + 20C C≥30pF : Q≥1000 (C:Nominal capacitance)				
Value	Compensating(Class1)	High Frequency Type		Refer	to detailed specification			
	High Permittivity (Class2) No		1	BJ, B7, C6, C7, D7: 2.5% max.				
					ss 1	Class 2		
			Standard		High Frequency Type	C≦10 µF	C>10 µF	
	Preconditioning				one	Thermal treatment (at 150°C for 1hr) Note 2		
Test	Measuring frequey		1MHz±10%		1GHz	1kHz±10%	120±10Hz	
Methods and	Measuring voltage Note	1	0.5 to 5Vrms		1±0.2Vrms	0.5±0.1Vrms		
Remarks	Bias application			None				
	High Frequency Type							
	Measuring equipment	: HP	4291A					
	Measuring jig	: HP	16192A					

				Temperature Characteristic [ppm/°C]			erance [ppm/°C]
		Standard	C□:	0	CG,CH, CJ, (СК	G: ±30 H: ±60
	Temperature Compensating(Class1)	Standard	U□ :	— 750	UJ, UK		J: ±120 K: ±250
		SL :	+350 to −100	0			
	High Frequency Type	Tem	Temperature Character		C] Tole	erance [ppm/°C]	
	Specified	nigh Frequency Type	C□:	0	CH		H: ±60
Specified Value				Specification	Capacitance	Reference	Temperature Range
value				opcomodicion	change	temperature	Tomporacaro riango
			BJ	В	±10%	20°C	−25 to +85°C
			В	X5R	±15%	25°C	-55 to +85°C
	U: 1 D :::::::: (OL 0)		В7	X7R	±15%	25°C	−55 to +125°C
	High Permittivity (Class2)		C6	X6S	±22%	25°C	−55 to +105°C
				X7S	±22%	25°C	−55 to +125°C
				X7S	+22/-33%	25°C	−55 to +125°C
			LD(※)	X5R	±15%	25°C	−55 to +85°C
			Note:	VID Low diete	rtion high value i	multilavar aaran	io consoiter

Class 1

Capacitance at 20° C and 85° C shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

$$\frac{(C_{85}-C_{20})}{C_{20}\times\Delta T} \times 10^{6} (ppm/^{\circ}C) \qquad \Delta T = 65$$

Test Methods and Remarks Class 2

Capacitance at each step shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following

Step	В	X5R, X7R, X6S, X7S, X7T				
1	Minimum operating temperature					
2	20°C	25°C				
3	Maximum operating temperature					

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 $\frac{(C-C_2)}{C_2} \times 100(\%)$

C : Capacitance in Step 1 or Step 3

C2 : Capacitance in Step 2

9. Deflection				
Temperature Compensating(Class1) Value	Temperature	Standard	Appearance Capacitance change	: No abnormality : Within $\pm 5\%$ or ± 0.5 pF, whichever is larger.
	Compensating(Class1)	High Frequency Type	Appearance Cpaitance change	: No abnormality : Within±0.5 pF
			Appearance	: No abnormality

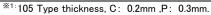
High Permittivity (Class2)

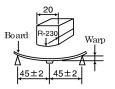
Capacitance change : Within ±12.5%(BJ, B7, C6, C7, D7, LD(※))

Note: XLD Low distortion high value multilayer ceramic capacitor

Test Methods and Remarks

	Multilayer Ceramic Capacitors			
	042, 063, ^{※1} 105 Type	The other types		
Board	Glass epoxy-resin substrate			
Thickness	0.8mm	1.6mm		
Warp	1mm (Soft Termination type:3mm)			
Duration	10 sec.			





(Unit: mm)

Capacitance measurement shall be conducted with the board bent

10. Body Stren	10. Body Strength			
	Temperature	Standard	-	
Specified Value	Compensating(Class1)	High Frequency Type	No mechanical damage.	
Value	High Permittivity (Class2)			
Test Methods and Remarks	High Frequency Type Applied force : 5N Duration : 10 sec.	Pres ← A →	R0.5 Pressing Jig Chip A	

11. Adhesive S	11. Adhesive Strength of Terminal Electrodes					
	Temperature	Standard				
Specified Value	Compensating(Class1)	High Frequency Type	No terminal separati	No terminal separation or its indication.		
	High Permittivity (Class2)					
		Multilayer Ceram	ic Capacitors	Hooked jig		
Test		042, 063 Type	105 Type or more			
Methods and	Applied force	2N	5N	R=05 Doard		
Remarks	Duration	30±5	sec.] ←Chip		
				Chip Chip		

12. Solderabilit	12. Solderability				
	Temperature	Standard			
Specified Value	Compensating(Class1)	High Frequency Type	At least 95%	At least 95% of terminal electrode is covered by new solder.	
Value	High Permittivity (Class2))			
- .	Eutectic s		older	Lead-free solder	
Test	Solder type	H60A or H	63A	Sn-3.0Ag-0.5Cu	
Methods and Remarks	Solder temperature	230±5°	С	245±3°C	
	Duration		4±1 sec.		

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13. Resistance	to Soldering				
Specified Value	Temperature	Standard	Appearance Capacitance change Q Insulation resistance Withstanding voltage	: No abnormality : Within ±2.5% or ±0 : Initial value : Initial value (between terminals)	.25pF, whichever is larger. : No abnormality
	Compensating(Class1)	High Frequency Type	Appearance : No abnormality Capacitancecange : Within ±2.5% Q : Initial value Insulation resistance Withstanding voltage : Unitial value (between terminals)		: No abnormality
	High Permittivity (Class2) Note 1		Appearance Capactace change Dissipation factor Insulation resistance Withstanding voltage Note: **LD Low distort	: No abormality : Within ±7.5%(BJ, B' : Initial value : Initial value (between terminals): tion high value multilaye	No abnormality
		042, 063 Type	1	05 Type	
	Preconditioning		None		
	Preheating	150°C, 1 to 2 min.		0°C, 2 to 5 min. 00°C, 2 to 5 min.	
	Solder temp.		270±5°C		
	Duration		3±0.5 sec.		
Γest	Recovery	6 to 24 hrs	S (Standard condition) N	loe 5	
Methods and Remarks				Class 2	
		042,063 Type		07, 212 Type	316, 325 Type
	Preconditioning	. ,,,,		(at 150°C for 1 hr) No	
	Preheating	150°C, 1 to 2 min.	80 to 10	0°C, 2 to 5 min.	80 to 100°C, 5 to 10 min. 150 to 200°C, 5 to 10 min.
	Solder temp.			70±5°C	
	Duration			±0.5 sec.	
	Recovery			ndard condition)Note 5	i

14. Temperatur	14. Temperature Cycle (Thermal Shock)						
	Temperature	Standard		Appearance Capacitance change Q Insulation resistance Withstanding voltage	: No abnormality : Within ±2.5% or ±0.25 : Initial value : Initial value (between terminals) : N	-	
Specified Value	Compensating(Class1)	High Frequency	[,] Туре	Appearance Capacitance change Q Insulation resistance Withstanding voltage	: No abnormality : Within ±0.25pF : Initial value : Initial value (between terminals) : N	o abnormality	
	High Permittivity (Class2) Note 1			Appearance Capacitance change Dissipation factor Insulation resistance Withstanding voltage Note: **LD Low distort	: No abnormality : Within ±7.5% (BJ, B7, : Initial value : Initial value (between terminals) : N ion high value multilayer c	o abnormality	
			C	Class 1		Class 2	
	Preconditioning	None			Thermal trea	tment (at 150°C for 1 hr) Note 2	
Test Methods and Remarks	1 cycle	Step Temperature 1 Minimum operating t 2 Normal temper 3 Maximum operating 4 Normal temperature			nting temperature emperature ting temperature	Time (min.) 30 ± 3 $2 \text{ to } 3$ 30 ± 3 $2 \text{ to } 3$	
	Number of cycles				5 times		
	Recovery	6 to 24 hr	S (Stan	dard condition)Note 5	24±2 hrs (5	Standard condition)Note 5	

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15. Humidity (Steady State)					
	Temperature Compensating(Class1	Standard)	Capacitance change Q	: No abnormality : Within $\pm 5\%$ or $\pm 0.5 pF$, whichever is larger. : $C < 10 pF$: $Q \ge 200 + 10 C$ $10 \le C < 30 pF$: $Q \ge 275 + 2.5 C$ $C \ge 30 pF$: $Q \ge 350$ (C : Nominal capacitance) : $1000 \text{ M} \Omega \text{ min}$.		
Specified Value		High Frequency Type	Appearance Capacitance change Insulation resistance	No abnormality Within $\pm 0.5 pF$, 1000 M Ω min.		
	High Permittivity (Cla	ass2) Note 1	Insulation resistance	: No abnormality : Within \pm 12.5% (BJ, B7, C6, C7, D7, LD($\stackrel{.}{\otimes}$)) : 5.0% max. (BJ, B7, C6, C7, D7, LD($\stackrel{.}{\otimes}$)) : 50 M $\Omega\mu$ F or 1000 M Ω whichever is smaller. on high value multilayer ceramic capacitor		
			ass 1	Class 2		
_		Standard	High Frequency Type			
Test			one co L o°o	Thermal treatment (at 150°C for 1 hr) Note 2		
Methods and Remarks	Temperature	40±2°C	60±2°C	40±2°C 90 to 95%RH		
Remarks	Humidity Duration		95%R⊓ 4/−0 hrs	90 to 95%RH 500+24/-0 hrs		
	Recovery		ard condition)Note 5	24±2 hrs (Standard condition) Note 5		

16. Humidity Lo	pading			
Specified Value	Temperature Compensating(Class1)	Standard	Appearance Capacitance change Q Insulation resistance	: No abnormality : Within $\pm 7.5\%$ or ± 0.75 pF, whichever is larger. : C < 30 pF : Q $\ge 100 + 10$ C/3 C ≥ 30 pF : Q ≥ 200 (C:Nominal capacitance) : 500 M Ω min.
		High Frequency Type	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$	
	High Permittivity(Class2) Note 1	Appearance Capacitance change Dissipation factor Insulation resistance Note: **LD Low distort	: No abnormality : Within \pm 12.5% (BJ, B7, C6, C7, D7, LD($\%$)) : 5.0% max. (BJ, B7, C6, C7, D7, LD($\%$)) : 25 M $\Omega\mu$ F or 500 M Ω whichever is smaller. cion high value multilayer ceramic capacitor
		C	Class 1	Class 2
		Standard	High Frequency Typ	pe All items
	Preconditioning		None	Voltage treatment (Rated voltage are applied for 1 hour at 40°C) Note 3
Test	Temperature	40±2°C	60±2°C	40±2°C
Methods and	Humidity	90 t	:o 95%RH	90 to 95%RH
Remarks	Duration	500+	24/-0 hrs	500+24/-0 hrs
	Applied voltage	Rate	d voltage	Rated voltage
	Charge/discharge current	50r	mA max.	50mA max.
	Recovery	6 to 24 hrs (Stan	dard condition)Note 5	24±2 hrs(Standard condition) Note 5

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17. High Tempe	erature Loading					
Specified Value	Temperature Compensating(Class1)	Standard	Appearance Capacitance change Q Insulation resistance	: $C < 10pF$: $Q \ge 200 + 10C$ $10 \le C < 30pF$: $Q \ge 275 + 2.5C$ $C \ge 30pF$: $Q \ge 350(C$: Nominal capacitance)		
		High Frequency Type	Appearance : No abnormaling the frequency Type		$\pm 3\%$ or ± 0.3 pF, whichever is larger.	
	High Permittivity(Class2) Note 1	Appearance Capacitance change Dissipation factor Insulation resistance Note: **LD Low dis*	: 5.0% max.(BJ, E	(BJ, B7, C6, C7, D 37, C6, C7, D7, LDG 00 MΩ whichever is tilayer ceramic capa	※)) s smaller.
		Clas	s 1	1 Class 2		
		Standard H	High Frequency Type	BJ, LD(※)	C6	B7, C7, D7
	Preconditioning	None		Voltage treatment (Twice the rated voltage shall be applied for 1 hour at 85°C, 105°C or 125°C) Note 3, 4		
Test	Temperature	Maximum operati	ng temperature	Maximum operating temperature		
Methods and	Duration	1000+48	/-0 hrs	1000+48/-0 hrs		
Remarks	Applied voltage	Rated vol	ltage × 2	Rated voltage × 2 Note 4		
	Charge/discharge current	50mA	max.	50mA max.		
	Recovery	6 to 24hr(Standard	condition) Note 5	24±2 hr	s (Standard condit	tion) Note 5
			Note	*LD Low distortion	n high value multil	ayer ceramic capacitor

Note 1 The figures indicate typical specifications. Please refer to individual specifications in detail.

- Note 2 Thermal treatment : Initial value shall be measured after test sample is heat-treated at $150 \pm 0/-10^{\circ}$ C for an hour and kept at room temperature for 24 ± 2 hours.
- Note 3 Voltage treatment: Initial value shall be measured after test sample is voltage—treated for an hour at both the temperature and voltage specified in the test conditions, and kept at room temperature for 24±2hours.
- Note 4 150% of rated voltage is applicable to some items. Please refer to their specifications for further information.
- Note 5 Standard condition: Temperature: 5 to 35°C, Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted under the following condition.

 Temperature: 20±2°C, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa Unless otherwise specified, all the tests are conducted under the

"standard condition".

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Medium-High Voltage Multilayer Ceramic Capacitor

RELIABILITY DATA

1. Operating Tempe	rature Range					
	Temperature Compensating(High Frequency type) CG(COG) : -55 to +125°C					
Specified Value	High permittivity X7R, X7S : −55 to +125°C X5 : −55 to +85°C B : −25 to +85°C					
2. Storage Tempera	ture Range					
	Temperature Compensating(High Frequency type) CG(C0G) : -55 to +125°C					
Specified Value	High permittivity X7R, X7S : -55 to +125°C X5R : -55 to +85°C B : -25 to +85°C					
3. Rated Voltage						
Specified Value	100VDC(HMK,HMJ), 250VDC(QMK,QMJ,QVS), 630VDC(SMK,SMJ)					
4. Withstanding Volt	tage (Between terminals)					
Specified Value	No breakdown or damage					
Test Methods and Remarks	Applied voltage : Rated voltage × 2.5 (HMK,HMJ), Rated voltage × 2 (QMK,QMJ,QVS), Rated voltage × 1.2 (SMK,SMJ) Duration : 1 to 5sec. Carge/discharge current : 50mA max.					
5. Insulation Resist						
Specified Value	Temperature Compensating(High Frequency type) $10000M\Omega\text{min}$ High permittivity					
	100M Ω μF or 10G Ω whichever is smaller.					
Test Methods and Remarks	Applied voltage : Rated voltage(HMK,HMJ, QMK,QMJ,QVS), 500V(SMK,SMJ) Duration : 60±5sec. Charge/discharge current : 50mA max.					

6. Capacitance (To	6. Capacitance (Tolerance)					
Specified Value	Temperature Compensating(High Frequency type) $ \pm 0.1 pF (C < 5pF) \pm 0.25pF (C < 10pF) \pm 0.5pF (5pF \le C < 10pF) \pm 2\%(C = 10pF) \pm 5\%(C \ge 10pF) $ High permittivity $ \pm 10\%, \ \pm 20\% $					
Test Methods and Remarks	Temperature Compensating(High Frequency type) Measuring frequency : 1MHz±10% Measuring voltage : 0.5 to 5Vrms Bias application : None					

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7. Q or Dissipation	Factor						
	Temperature Compensating(High Frequency type)						
	C<30pF:Q≧800+20C						
	C≧30pF: Q≧1400	C:Normal Capacitance(/pF)					
Specified Value							
	High permittivity						
	3.5%max (HMK,HMJ)						
	2.5%max(QMK,QMJ, SMK,SMJ)						
	Temperature Compensating(High Frequency type)						
	Measuring frequency	: 1MHz±10%					
	Measuring voltage	: 0.5 to 5Vrms					
Test Methods and	Bas application	: None					
Remarks	High permittivity						
	Measuring frequency	: 1kHz±10%					
	Measuring voltage	: 1±0.2Vrms					
	Bas application	: None					

8. Temperature Cha	aracteristic of	F Capacitance				
	Temperature Compensating(High Frequency type) COG :±30ppm(25 to +125°C)					
Specified Value	High permittivity B : ±10%(-25 to +85°C) X5R : ±15%(-55 to +85°C) X7R : ±15%(-55 to +125°C) X7S : ±22%(-55 to +125°C)					
	Capacitance following equal $\frac{(C_{85}\!-\!C_{25})}{C_{25}\!\times\!\Delta\!T}$ High permitt	uation.) × 10 ⁶ × [ppm/°C] tivity e value at each step sl	nall be measured in therm	al equilibrium, and the temperature characteristic shall be calculated from the		
Test Methods and Remarks	Step	В	X5R, X7R, X7S			
Remarks	1	Minimum operat	ting tempeature			
	2	20°C	25°C			
	3 Maximum operating temperature					
	=	× 100(%) itance value in Step 1	or Step 3			

9. Deflection						
Specified Value	Temperature Compensating(High Frequency type) Appearance : No abnormality Capacitance change : ±5% or ±0.5pF, whichever is larger.					
opecined value	High permittivity Appearance : No abnormality Capacitance change : Within±10%					
Test Methods and Remarks	Warp : 1mm (Soft Termination type:3mm) Duration : 10sec. Test board : Glass epoxy-resin substrate Thicknss : 1.6mm Board Warp Warp (Unit: mm)					
	Capacitance measurement shall be conducted with the board bent.					

C2 : Capacitance value in Step 2

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10. Adhesive Strength of Terminal Electrodes Specified Value No terminal separation or its indication. Temperature Compensating(High Frequency type) Applied force : 2N Hooked jig Duration : 10±5sec. Board Test Methods and Remarks High permittivity Applied force : 5N Hooked jig Duration : 30±5sec. Board

11. Solderability								
Specified Value	Specified Value At least 95% of terminal electrode is covered by new solder							
		Eutectic solder	Lead-free solder					
Test Methods and	Solder type	H60A or H63A	Sn-3.0Ag-0.5Cu					
Remarks	Solder temperature	230±5°C	245±3°C					
	Duration	4±1	sec.					

12. Resistance to S	12. Resistance to Soldering							
	Temperature Compensating(High Frequency type)							
	Appearance	: No abnormality						
	Capacitance change	: C※≦10pF :±0.25pF C※>10pF :±2.5% ※Normal capacitance						
	Insulation resistance	: Initial value						
	Withstanding voltage	(between terminals): No abnormality						
Specified Value	High permittivity							
	Appearance	: No abnormality						
	Capacitance change	: Within±15%(HMK,HMJ), ±10%(QMK,QMJ, SMK,SMJ)						
	Dissipation factor	: Inital value						
	Insulation resistance	: Initial value						
	Withstanding voltage	(between terminals): No abnormality						
	Preconditioning	: Thermal treatment(at 150°C for 1hr) Note1 (Only High permittivity)						
Test Methods and	Solder temperature	: 270±5℃						
Remarks	Duration	: 3±0.5sec.						
1 Ciliai No	Preheating conditions	: 80 to 100°C, 2 to 5 min. 150 to 200°C, 2 to 5min.						
	Recovery	: 24 ± 2 hrs under the stadard condition Note3						

13. Temperature C	1				
	Temperati	ure Compens	ating(High Frequency type)		
	Appearance		: No abnormality		
		ce change	: C※≦10pF:±0.25% C※>10pF:±2	2.5%	
	Insulation	resistance	: Initial value		
	Withstand	ing voltage	(between terminals): No abnormality		
Specified Value	High permittivity				
	Appearance		: No abnormality		
	Capacitance change		: Within±15%(HMK,HMJ), ±7.5%(QMK,QMJ, SMK,SMJ)		
	Dissipation factor		: Initial value		
	Insulation	resistance	: Initial value		
	Withstand	nding voltage (between terminals): No abnormality			
	Precondit	ioning : Therr	mal treatment (at 150°C for 1hr) Note1		
	Conditions for 1 cycle				
	Step		temperature(°C)	Time (min.)	
Test Methods and	1		Minimum operating temperature	30±3min.	
Remarks	2		Normal temperature	2 to 3min.	
Ciliains	3	Maximum operating temperature		30±3min.	
	4		Normal temperature	2 to 3min.	

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14. Humidity (Stea	ady state)								
	Temperature Compensating(High Frequency type)								
	Appearance	: No abnormality							
	Capacitance change	: C※≦10pF :±0.5pF C※>10pF :±5% ※Normal capacitance							
	Insulation resistance	: 1000M Ωmin							
Specified Value	High permittivity								
	Appearance	: No abnormality							
	Capacitance change	: Within±15%							
	Dissipation factor	: 7%max(HMK,HMJ), 5%max(QMK,QMJ, SMK,SMJ).							
	Insulation resistance	: 25M $\Omega\mu\!\!\!\!/F$ or 1000M Ω whichever is smaller.							
	Preconditioning	: Thermal treatment(at 150°C for 1hr) Note1 (Only High permittivity)							
Test Methods and	Temperature	: 40±2℃							
Remarks	Humidity	: 90 to 95%RH							
Remarks	Duration	:500 + 24/-0 hrs							
	Recovery	: 24 ± 2 hrs under the standard condition Note 3							

15. Humidity Loadin	ng	
	Temperature Compensating	(High Frequency type)
	Appearance	: No abnormality
	Capacitance change	: C $\frac{5}{2.0p}$ F: $\pm 0.4p$ F 2.0 p F < C $\frac{5}{2}$ 10 p F: $\pm 0.75p$ F C $\frac{5}{2}$ >10 p F: ± 7.5 %
		: ※Normal capacitance
	Insulation resistance	: 500M Ωmin
Specified Value		
	High permittivity	
	Appearance	: No abnormality
	Capacitance change	: Within±15%
	Dissipation factor	: 7%max(HMK,HMJ), 5%max(QMK,QMJ, SMK,SMJ).
	Insulation resistance	: 10M $\Omega\mu\!\!\!/F$ or 500M Ω whichever is smaller.
	According to JIS 5102 claus	se 9.9.
	Preconditioning	: Voltage treatment Note2 (Only High permittivity)
	Temperature	: 40±2°C
Test Methods and	Humidity	: 90 to 95%RH
Remarks	Applied voltage	: Rated voltage
	Charge/discharge current	: 50mA max.
	Duration	: 500 + 24/-0 hrs
	Recovery	: 24±2hrs under the standard condition Note3

16. High Temperatu	I						
	Temperature Compensating(High Frequency type)						
	Appearance	: No abnormality					
	Capacitance change	: C‰≦10pF :±0.3pF C‰>10pF :±3%					
	Insulation resistance	:1000M Ωmin					
Specified Value	High permittivity						
	Appearance	: No abnormality					
	Capacitance change	: Within±15%					
	Dissipation factor	: 7%max(HMK,HMJ), 5%max(QMK,QMJ, SMK,SMJ).					
	Insulation resistance	: 50M $\Omega ot\!$					
	According to JIS 5102 claus	se 9.10.					
	Preconditioning	: Voltage treatment Note2 (Only High permittivity)					
Test Methods and	Temperature	: Maximum operating temperature					
Remarks	Applied voltage	: Rated voltage × 2(HMK,HMJ,QVS) Rated voltage × 1.5(QMK,QMJ) Rated voltage × 1.2(SMK,SMJ)					
Remarks	Charge/discharge current	: 50mA max.					
	Duration	: 1000 + 24/-0 hrs					
	Recovery	: 24±2hrs under the standard condition Note3					

Note1 Thermal treatment : Initial value shall be measured after test sample is heat-treated at $150 \pm 0/-10^{\circ}\text{C}$ for an hour and kept at room temperature

for 24±2hours.

Note2 Voltage treatment : Initial value shall be measured after test sample is voltage-treated for an hour at both the temperature and voltage specified in

the test conditions, and kept at room temperature for 24 \pm 2hours.

Note3 Standard condition $\,:$ Temperature: 5 to 35°C, Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa

When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted

under the following condition.

Temperature: $20\pm2^{\circ}$ C, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa Unless otherwise specified, all the tests are conducted under the "standard condition".

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Precautions on the use of Multilayer Ceramic Capacitors

■PRECAUTIONS

1. Circuit Design

- ◆ Verification of operating environment, electrical rating and performance
 - A malfunction of equipment in fields such as medical, aerospace, nuclear control, etc. may cause serious harm to human life or have severe social ramifications.

Therefore, any capacitors to be used in such equipment may require higher safety and reliability, and shall be clearly differentiated from them used in general purpose applications.

Precautions

- ◆Operating Voltage (Verification of Rated voltage)
 - 1. The operating voltage for capacitors must always be their rated voltage or less.
 - If an AC voltage is loaded on a DC voltage, the sum of the two peak voltages shall be the rated voltage or less.
 - For a circuit where an AC or a pulse voltage may be used, the sum of their peak voltages shall also be the rated voltage or less.
 - 2. Even if an applied voltage is the rated voltage or less reliability of capacitors may be deteriorated in case that either a high frequency AC voltage or a pulse voltage having rapid rise time is used in a circuit.

2. PCB Design

Precautions

- ◆Pattern configurations (Design of Land-patterns)
- 1. When capacitors are mounted on PCBs, the amount of solder used (size of fillet) can directly affect the capacitor performance. Therefore, the following items must be carefully considered in the design of land patterns:
 - (1) Excessive solder applied can cause mechanical stresses which lead to chip breaking or cracking. Therefore, please consider appropriate land-patterns for proper amount of solder.
 - (2) When more than one component are jointly soldered onto the same land, each component's soldering point shall be separated by solder-resist.
- ◆Pattern configurations (Capacitor layout on PCBs)

After capacitors are mounted on boards, they can be subjected to mechanical stresses in subsequent manufacturing processes (PCB cutting, board inspection, mounting of additional parts, assembly into the chassis, wave soldering of the boards, etc.). For this reason, land pattern configurations and positions of capacitors shall be carefully considered to minimize stresses.

◆Pattern configurations (Design of Land-patterns)

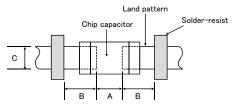
The following diagrams and tables show some examples of recommended land patterns to prevent excessive solder amounts.

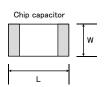
- (1) Recommended land dimensions for typical chip capacitors
- Multilayer Ceramic Capacitors : Recommended land dimensions (unit: mm)

Wave-soldering

Type		107	212	316	325
Size	L	1.6	2.0	3.2	3.2
Size	W	0.8	1.25	1.6	2.5
Α		0.8 to 1.0	1.0 to 1.4	1.8 to 2.5	1.8 to 2.5
В		0.5 to 0.8	0.8 to 1.5	0.8 to 1.7	0.8 to 1.7
С		0.6 to 0.8	0.9 to 1.2	1.2 to 1.6	1.8 to 2.5

Land patterns for PCBs





Technical considerations

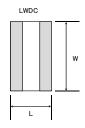
Reflow-soldering

	Tellow Soldering								
	Туре	042	063	105	107	212	316	325	432
Si	L	0.4	0.6	1.0	1.6	2.0	3.2	3.2	4.5
SI	W	0.2	0.3	0.5	0.8	1.25	1.6	2.5	3.2
	Α	0.15 to 0.25	0.20 to 0.30	0.45 to 0.55	0.8 to 1.0	0.8 to 1.2	1.8 to 2.5	1.8 to 2.5	2.5 to 3.5
	В	0.15 to 0.20	0.20 to 0.30	0.40 to 0.50	0.6 to 0.8	0.8 to 1.2	1.0 to 1.5	1.0 to 1.5	1.5 to 1.8
	С	0.15 to 0.30	0.25 to 0.40	0.45 to 0.55	0.6 to 0.8	0.9 to 1.6	1.2 to 2.0	1.8 to 3.2	2.3 to 3.5

 $Note: Recommended \ land \ size \ might \ be \ different \ according \ to \ the \ allowance \ of \ the \ size \ of \ the \ product.$

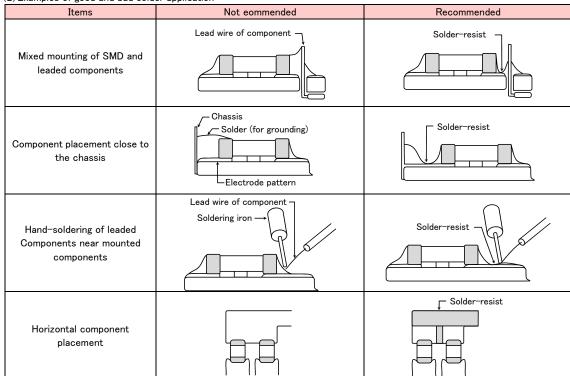
●LWDC: Recommended land dimensions for reflow-soldering (unit: mm)

Ту	ре	105	107	212
Size	L	0.52	0.8	1.25
Size	W	1.0	1.6	2.0
ļ	٨	0.18 to 0.22	0.25 to 0.3	0.5 to 0.7
E	8	0.2 to 0.25	0.3 to 0.4	0.4 to 0.5
С		0.9 to 1.1	1.5 to 1.7	1.9 to 2.1



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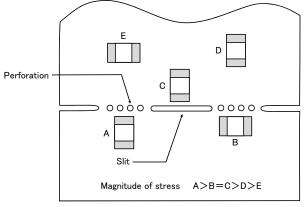
(2) Examples of good and bad solder application



- ◆Pattern configurations (Capacitor layout on PCBs)
 - 1-1. The following is examples of good and bad capacitor layouts; capacitors shall be located to minimize any possible mechanical stresses from board warp or deflection.

Items	Not recommended	Recommended
Deflection of board		Place the product at a right angle to the direction of the anticipated mechanical stress.

1-2. The amount of mechanical stresses given will vary depending on capacitor layout. Please refer to diagram below.



1-3. When PCB is split, the amount of mechanical stress on the capacitors can vary according to the method used. The following methods are listed in order from least stressful to most stressful: push-back, slit, V-grooving, and perforation. Thus, please consider the PCB, split methods as well as chip location.

3. Mounting

- ◆Adjustment of mounting machine
 - 1. When capacitors are mounted on PCB, excessive impact load shall not be imposed on them.
 - 2. Maintenance and inspection of mounting machines shall be conducted periodically.

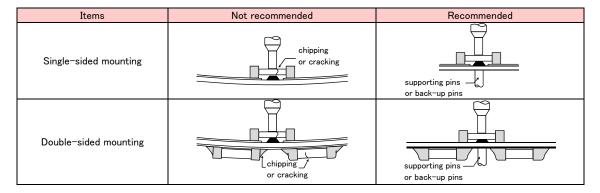
Precautions Selection of Adhesives

1. When chips are attached on PCBs with adhesives prior to soldering, it may cause capacitor characteristics degradation unless the following factors are appropriately checked: size of land patterns, type of adhesive, amount applied, hardening temperature and hardening period. Therefore, please contact us for further information.

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◆Adjustment of mounting machine

- 1. When the bottom dead center of a pick-up nozzle is too low, excessive force is imposed on capacitors and causes damages. To avoid this, the following points shall be considerable.
 - (1) The bottom dead center of the pick-up nozzle shall be adjusted to the surface level of PCB without the board deflection.
 - (2) The pressure of nozzle shall be adjusted between 1 and 3 N static loads.
 - (3) To reduce the amount of deflection of the board caused by impact of the pick-up nozzle, supporting pins or back-up pins shall be used on the other side of the PCB. The following diagrams show some typical examples of good and bad pick-up nozzle placement:



Technical considerations

2. As the alignment pin is worn out, adjustment of the nozzle height can cause chipping or cracking of capacitors because of mechanical impact on the capacitors.

To avoid this, the monitoring of the width between the alignment pins in the stopped position, maintenance, check and replacement of the pin shall be conducted periodically.

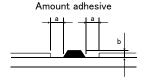
◆Selection of Adhesives

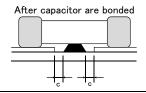
Some adhesives may cause IR deterioration. The different shrinkage percentage of between the adhesive and the capacitors may result in stresses on the capacitors and lead to cracking. Moreover, too little or too much adhesive applied to the board may adversely affect components. Therefore, the following precautions shall be noted in the application of adhesives.

- (1) Required adhesive characteristics
 - a. The adhesive shall be strong enough to hold parts on the board during the mounting & solder process.
 - b. The adhesive shall have sufficient strength at high temperatures.
 - c. The adhesive shall have good coating and thickness consistency.
 - d. The adhesive shall be used during its prescribed shelf life.
 - e. The adhesive shall harden rapidly.
 - f. The adhesive shall have corrosion resistance.
 - g. The adhesive shall have excellent insulation characteristics.
 - h. The adhesive shall have no emission of toxic gasses and no effect on the human body.
- $\begin{tabular}{ll} (2) The recommended amount of adhesives is as follows; \\ \end{tabular}$

[Recommended condition]

Figure	212/316 case sizes as examples	
а	0.3mm min	
b	100 to 120 μm	
С	Adhesives shall not contact land	





4. Soldering

Precautions

Technical

considerations

◆Selection of Flux

Since flux may have a significant effect on the performance of capacitors, it is necessary to verify the following conditions prior to use;

- (1) Flux used shall be less than or equal to 0.1 wt%(in CI equivalent) of halogenated content. Flux having a strong acidity content shall not be applied.
- (2) When shall capacitors are soldered on boards, the amount of flux applied shall be controlled at the optimum level.
- (3) When water-soluble flux is used, special care shall be taken to properly clean the boards.

◆ Soldering

Temperature, time, amount of solder, etc. shall be set in accordance with their recommended conditions.

Sn-Zn solder paste can adversely affect MLCC reliability.

Please contact us prior to usage of Sn-Zn solder.

◆Selection of Flux

1-1. When too much halogenated substance (Chlorine, etc.) content is used to activate flux, or highly acidic flux is used, it may lead to corrosion of terminal electrodes or degradation of insulation resistance on the surfaces of the capacitors.

- 1-2. Flux is used to increase solderability in wave soldering. However if too much flux is applied, a large amount of flux gas may be emitted and may adversely affect the solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system.
- 1-3. Since the residue of water-soluble flux is easily dissolved in moisture in the air, the residues on the surfaces of capacitors in high humidity conditions may cause a degradation of insulation resistance and reliability of the capacitors. Therefore, the cleaning methods and the capability of the machines used shall also be considered carefully when water-soluble flux is used.

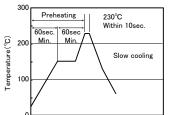
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◆Soldering

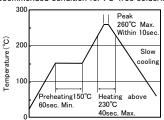
- · Ceramic chip capacitors are susceptible to thermal shock when exposed to rapid or concentrated heating or rapid cooling.
- · Therefore, the soldering must be conducted with great care so as to prevent malfunction of the components due to excessive thermal shock
- Preheating: Capacitors shall be preheated sufficiently, and the temperature difference between the capacitors and solder shall be within 100 to 130°C.
- · Cooling: The temperature difference between the capacitors and cleaning process shall not be greater than 100°C.

[Reflow soldering]

[Recommended conditions for eutectic soldering]

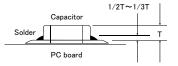


[Recommended condition for Pb-free soldering]



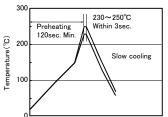
Caution

- \bigcirc The ideal condition is to have solder mass(fillet)controlled to 1/2 to 1/3 of the thickness of a capacitor.
- ②Because excessive dwell times can adversely affect solderability, soldering duration shall be kept as close to recommended times as possible.
- 3 Allowable number of reflow soldering: 2 times max.

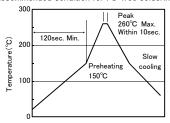


[Wave soldering]

[Recommended conditions for eutectic soldering]



[Recommended condition for Pb-free soldering]

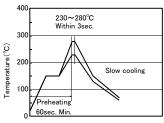


Caution

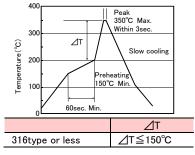
- ①Wave soldering must not be applied to capacitors designated as for reflow soldering only.
- ②Allowable number of wave soldering: 1 times max.

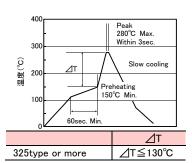
[Hand soldering]

[Recommended conditions for eutectic soldering]



[Recommended condition for Pb-free soldering]





Caution

- ①Use a 50W soldering iron with a maximum tip diameter of 1.0 mm.
- 2The soldering iron shall not directly touch capacitors.
- 3 Allowable number of hand soldering: 1 times max.

5. Cleaning Cleaning conditions 1. When PCBs are cleaned after capacitors mounting, please select the appropriate cleaning solution in accordance with the intended use Precautions of the cleaning. (e.g. to remove soldering flux or other materials from the production process.) 2. Cleaning condition shall be determined after it is verified by using actual cleaning machine that the cleaning process does not affect capacitor's characteristics. 1. The use of inappropriate cleaning solutions can cause foreign substances such as flux residue to adhere to capacitors or deteriorate their outer coating, resulting in a degradation of the capacitor's electrical properties (especially insulation resistance). 2. Inappropriate cleaning conditions (insufficient or excessive cleaning) may adversely affect the performance of the capacitors. In the case of ultrasonic cleaning, too much power output can cause excessive vibration of PCBs which may lead to the Technical cracking of capacitors or the soldered portion, or decrease the terminal electrodes' strength. Therefore, the following conditions shall considerations be carefully checked; Ultrasonic output: 20 W/Q or less Ultrasonic frequency: 40 kHz or less Ultrasonic washing period: 5 min. or less

6. Resin coating and mold

Precautions

- 1. With some type of resins, decomposition gas or chemical reaction vapor may remain inside the resin during the while left under normal storage conditions resulting in the deterioration of the capacitor's performance.
- 2. When a resin's hardening temperature is higher than capacitor's operating temperature, the stresses generated by the excessive heat may lead to damage or destruction of capacitors.

The use of such resins, molding materials etc. is not recommended.

7. Handling

♦Splitting of PCB

- 1. When PCBs are split after components mounting, care shall be taken so as not to give any stresses of deflection or twisting to the board.
- 2. Board separation shall not be done manually, but by using the appropriate devices.

Precautions

◆Mechanical considerations

Be careful not to subject capacitors to excessive mechanical shocks.

- (1) If ceramic capacitors are dropped onto a floor or a hard surface, they shall not be used.
- (2) Please be careful that the mounted components do not come in contact with or bump against other boards or components.

8. Storage conditions

◆Storage

- 1. To maintain the solderability of terminal electrodes and to keep packaging materials in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible.
 - Recommended conditions

Precautions

Ambient temperature : Below 30°C
Humidity : Below 70% RH

The ambient temperature must be kept below 40° C. Even under ideal storage conditions, solderability of capacitor is deteriorated as time passes, so capacitors shall be used within 6 months from the time of delivery.

- •Ceramic chip capacitors shall be kept where no chlorine or sulfur exists in the air.
- 2. The capacitance values of high dielectric constant capacitors will gradually decrease with the passage of time, so care shall be taken to design circuits. Even if capacitance value decreases as time passes, it will get back to the initial value by a heat treatment at 150°C for 1hour.

Technical considerations

If capacitors are stored in a high temperature and humidity environment, it might rapidly cause poor solderability due to terminal oxidation and quality loss of taping/packaging materials. For this reason, capacitors shall be used within 6 months from the time of delivery. If exceeding the above period, please check solderability before using the capacitors.

**RCR-2335B(Safety Application Guide for fixed ceramic capacitors for use in electronic equipment) is published by JEITA.

Please check the guide regarding precautions for deflection test, soldering by spot heat, and so on.

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